





#### SURFACE MOUNT SWITCHING DIODE ARRAY

#### **Features**

- Fast Switching Speed
- Small Surface Mount Package
- Low Reverse Recovery Time for Fast Switching
- Two "BAV99" Circuits In One Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

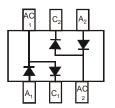
## **Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (3)
- Polarity: See Diagram
- Weight: 0.006 grams (Approximate)

**SOT363** 



Top View



Top View Internal Schematic

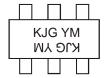
### Ordering Information (Note 5)

| Ī | Part Number  | Qualification | Case   | Packaging        |
|---|--------------|---------------|--------|------------------|
|   | BAV99DWQ-7-F | Automotive    | SOT363 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product\_compliance\_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



KJG = Product Type Marking Code YM = Date Code Marking Y = Year (ex: D = 2016) M = Month (ex: 9 = September)

Date Code Key

| Year  | 2012 | 2013 | 2014 | 2015 | 2016 | 2017 | 2018 | 2019 | 2020 | 2021 | 2022 | 2023 |
|-------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code  | Z    | Α    | В    | С    | D    | Е    | F    | G    | Н    | I    | J    | K    |
|       |      |      |      |      |      |      |      |      |      |      |      |      |
| Month | Jan  | Feb  | Mar  | Apr  | May  | Jun  | Jul  | Aug  | Sep  | Oct  | Nov  | Dec  |



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

| Characteristic   |   | Symbol           | Value | Unit |
|--|---|------------------|-------|------|
| Non-Repetitive Peak Reverse Voltage  | $V_{RM}$  | 100              | V     |      |
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage | V <sub>RRM</sub><br>V <sub>R</sub> WM<br>V <sub>R</sub> | 75               | V     |      |
| RMS Reverse Voltage  | V <sub>R(RMS)</sub>                                     | 53               | V     |      |
| Forward Continuous Current (Note 6)  | I <sub>FM</sub>   | 215              | mA    |      |
|  |   | 2.0              |       |      |
| Non-Repetitive Peak Forward Surge Current  | @ t = 1.0ms   | I <sub>FSM</sub> | 1.0   | A    |
|  |   | 0.5              |       |      |

## **Thermal Characteristics**

| Characteristic                                      | Symbol                            | Value       | Unit |
|---|-----------------------------------|-------------|------|
| Power Dissipation (Note 6)                          | P <sub>D</sub>                    | 200         | mW   |
| Power Dissipation (Note 7)                          | P <sub>D</sub>                    | 300         | mW   |
| Thermal Resistance Junction to Ambient Air (Note 6) | $R_{	heta JA}$                    | 625         | °C/W |
| Thermal Resistance Junction to Ambient Air (Note 7) | $R_{	heta JA}$                    | 417         | °C/W |
| Operating and Storage Temperature Range             | T <sub>J</sub> , T <sub>STG</sub> | -65 to +150 | °C   |

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

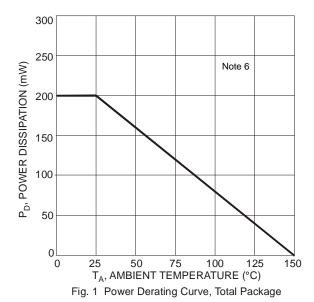
| Characteristic                     | Symbol          | Min | Max   | Unit | Test Condition   |
|------------------------------------|-----------------|-----|-------|------|--|
| Reverse Breakdown Voltage (Note 8) | $V_{(BR)R}$     | 75  | _     | V    | $I_R = 2.5 \mu A$  |
|                                    | V <sub>F</sub>  | _   | 0.715 | V    | $I_F = 1.0 \text{mA}$  |
| Forward Voltage                    |                 | _   | 0.855 |      | $I_F = 10mA$   |
| o ward voltage                     | ٧F              | _   | 1.0   |      | $I_F = 50 \text{mA}$   |
|                                    |                 | _   | 1.25  |      | I <sub>F</sub> = 150mA   |
|                                    | I <sub>R</sub>  | _   | 2.5   | μΑ   | $V_R = 75V$  |
| Reverse Current (Note 8)           |                 | _   | 50    |      | $V_R = 75V, T_J = +150^{\circ}C$   |
| Reverse Current (Note o)           |                 | _   | 30    |      | $V_R = 25V, T_J = +150^{\circ}C$   |
|                                    |                 | _   | 25    | nA   | $V_R = 20V$  |
| Total Capacitance                  | CT              | _   | 2.0   | pF   | $V_R = 0, f = 1.0MHz$  |
| Reverse Recovery Time              | t <sub>RR</sub> | _   | 4.0   | ns   | $I_F = I_R = 10 \text{mA},$<br>$I_{RR} = 0.1 \times I_R, R_L = 100 \Omega$ |

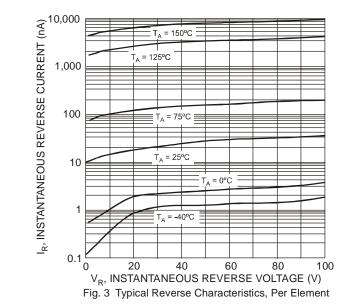
Notes:

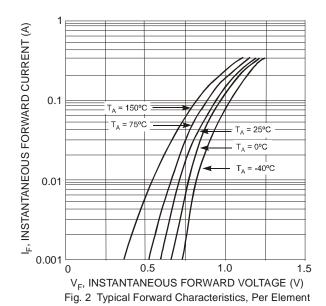
- 6. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on our website at http://www.diodes.com/package-outlines.html.
- 7. Device mounted on Alumina PCB, 0.4 inch x 0.30 inch x 0.024 inch; pad layout as shown on our website at http://www.diodes.com/package-outlines.html.

  8. Short duration pulse test used to minimize self-heating effect.









2.0 1.8 1.6 C<sub>T</sub>, TOTAL CAPACITANCE (pF) 1.4 1.2 1.0 8.0 0.6 0.4 0.2 0.0 30

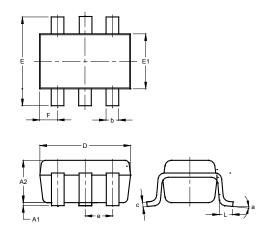
 $V_R$ , DC REVERSE VOLTAGE (V) Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

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# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.



|                      | SOT363    |      |       |  |  |  |  |  |
|----------------------|-----------|------|-------|--|--|--|--|--|
| Dim                  | Min       | Max  | Тур   |  |  |  |  |  |
| A1                   | 0.00      | 0.10 | 0.05  |  |  |  |  |  |
| A2                   | 0.90      | 1.00 | 1.00  |  |  |  |  |  |
| b                    | 0.10      | 0.30 | 0.25  |  |  |  |  |  |
| С                    | 0.10      | 0.22 | 0.11  |  |  |  |  |  |
| D                    | 1.80      | 2.20 | 2.15  |  |  |  |  |  |
| Е                    | 2.00      | 2.20 | 2.10  |  |  |  |  |  |
| E1                   | 1.15      | 1.35 | 1.30  |  |  |  |  |  |
| е                    | 0.650 BSC |      |       |  |  |  |  |  |
| F                    | 0.40      | 0.45 | 0.425 |  |  |  |  |  |
| L                    | 0.25      | 0.40 | 0.30  |  |  |  |  |  |
| а                    | 0°        | 8°   |       |  |  |  |  |  |
| All Dimensions in mm |           |      |       |  |  |  |  |  |

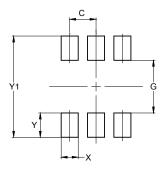
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**April 2016** 



## Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



| Dimensions | Value<br>(in mm) |  |  |
|------------|------------------|--|--|
| С          | 0.650            |  |  |
| G          | 1.300            |  |  |
| Х          | 0.420            |  |  |
| Y          | 0.600            |  |  |
| Y1         | 2.500            |  |  |

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